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modifying the composition of atomic planes in the material around an interface between two layers of the multi-layer material.

Please add the following new claims:

- -\f11. (New) Process according to claim 1, wherein said irradiation is capable of modifying the composition around said interface between two layers without measurably increasing the surface roughness of the multi-layer material.
- 12. (New) Process according to claim 1, wherein said irradiation is capable of modifying chemical composition of only one of the layers.
- 13. (New) Process according to claim 1, wherein chemical composition of at least one of the layers remains unchanged after the irradiation.
- 14. (New) A process for performing irradiation on a multi-layer material having a buried layer disposed between at least one top layer and at least one bottom layer, said process comprising:

selecting one or more regions of the multi-layer/material having a width in the order of 1 micrometer or less; and

irradiating the selected regions of the multi-layer material with (1) a beam of light ions having an energy of the order of or less than a hundred keV and (2) irradiation dose controlled so as to be a few 10¹⁶ ions/cm² or less such that the irradiation modifies the buried layer of the multi-layer material.

- 15. (New) Process according to claim 14, wherein the irradiation is capable of modifying the buried layer of the multi-layer material without significantly interacting with atoms of the at least one top layer of the multi-layer material.
- 16/ (New) Process according to claim 14, wherein the at least one top layer comprises five atomic planes or less.

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- 17. (New) Process according to claim 14, wherein the irradiation modifies a magnetic property of the buried layer.
- 18. (New) Process according to claim 14, wherein the irradiation is capable of modifying the buried layer of the multi-layer/material without significantly effecting an optical reflectivity of the at least one top layer of the multi-layer material.
- 19. (New) Process according to claim 14, wherein said irradiation is capable of modifying the magnetic property of the buried layer without measurably increasing the surface roughness of the multi-layer material.